

2 Amp. Surface Mounted Schottky Barrier Rectifier

<p>Dimensions in mm.</p> <p>CASE: SMB/DO-214AA (Plastic)</p> <p>Week code Year code Type No. Class</p> <p>Standard soldering pad</p>	<p>Voltage 20 V to 60 V</p> <p>Current 2.0 A</p>	<ul style="list-style-type: none"> • Metal Silicon Junction, majority carrier conduction • High current capability, low forward voltage drop • Guardring for overvoltage protection • Low power loss, high efficiency • High surge capability • Plastic material carries U/L recognition 94VO • Low profile package • Easy pick and place
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Maximum Ratings, according to IEC publication No. 134

		FSS22	FSS23	FSS24	FSS25	FSS26
Marking Code		B1	B2	B3	B4	B5
V_{RRM}	Peak recurrent reverse voltage (V)	20	30	40	50	60
V_{RMS}	Maximum RMS voltage (V)	14	21	28	35	42
V_{DC}	Maximum DC blocking voltage (V)	20	30	40	50	60
$I_{F(AV)}$	Maximum average Forward current.	2 A				
I_{FSM}	8.3 ms. peak forward surge current (Jedec Method)	50 A				
T_j	Operating temperature range	- 65 to + 125 °C			- 65 to + 150 °C	
T_{stg}	Storage temperature range	- 65 to + 150 °C				

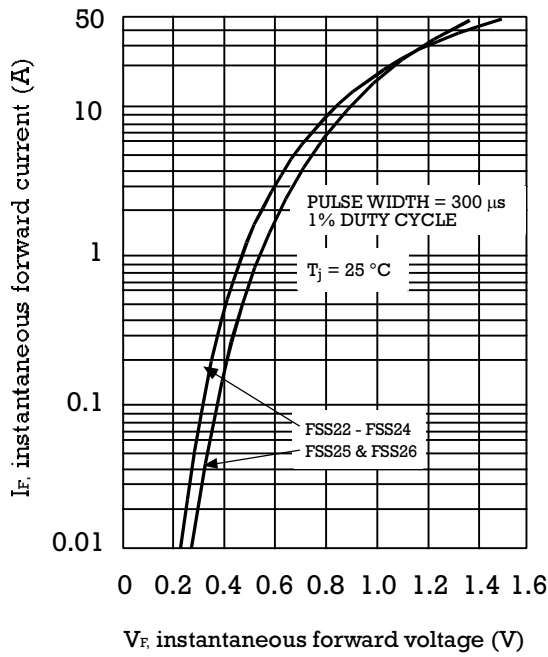
Electrical Characteristics at $T_{amb} = 25\text{ °C}$

V_F	Max. forward voltage drop at $I_F = 2.0\text{ A}$ ⁽¹⁾	0.55 V	0.70 V
I_R	Max. Instantaneous reverse current at V_{RRM} ⁽¹⁾	$T_a = 25\text{ °C}$	0.5 mA
		$T_a = 100\text{ °C}$	20 mA
R_{thj-a} R_{thj-l}	Maximum Thermal Resistance	75 °C/W 17 °C/W	10 mA

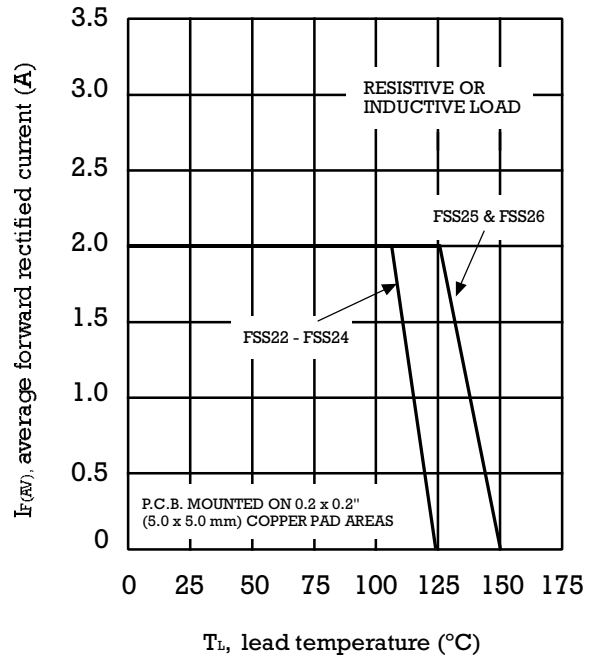
NOTE: Thermal Resistance from junction to lead or to ambient PCB mounted with 5x5 mm copper pads areas.

(1) Pulse test: 300µs pulse width, 1% duty cycle.

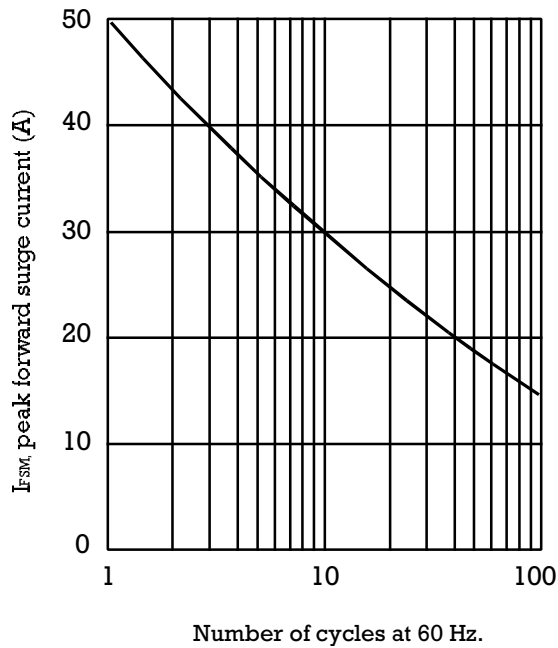
TYPICAL FORWARD CHARACTERISTIC



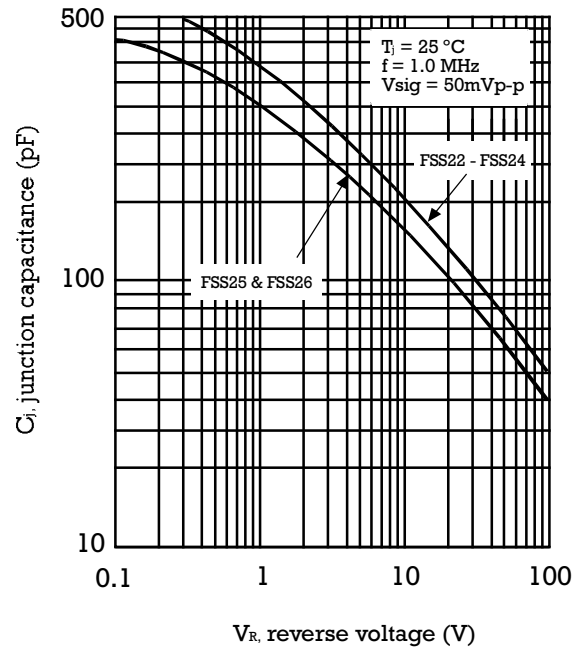
FORWARD CURRENT DERATING CURVE



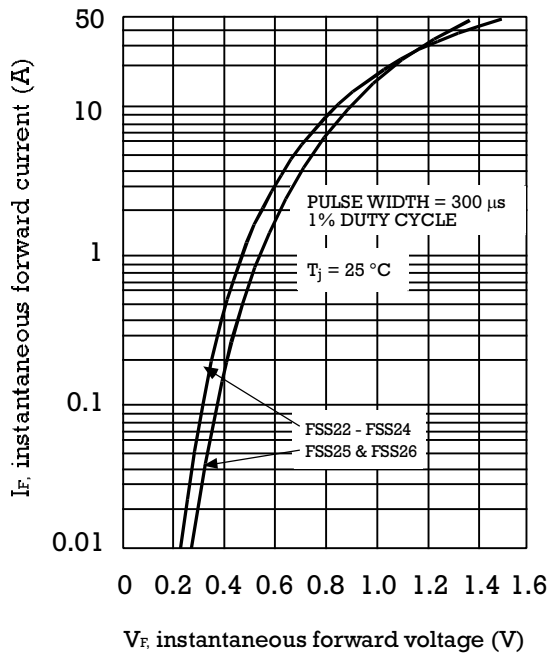
MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



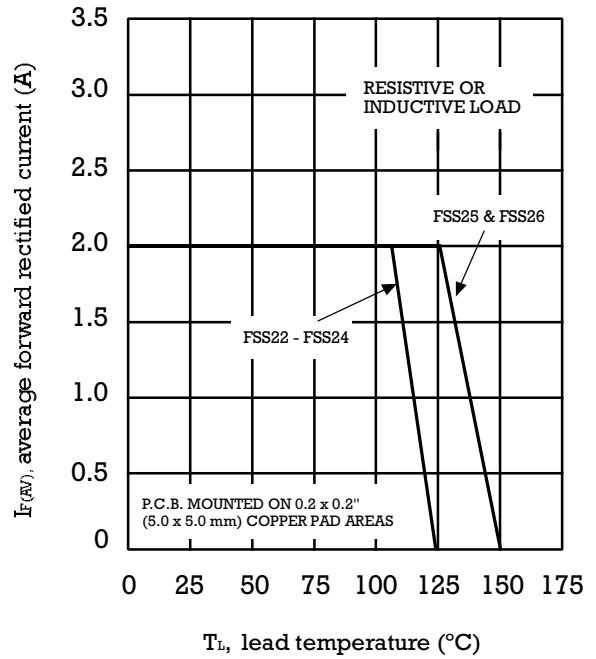
TYPICAL JUNCTION CAPACITANCE



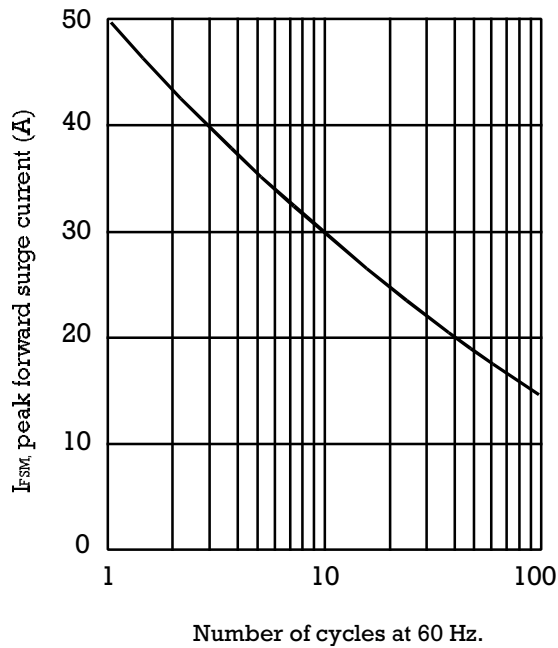
TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



TYPICAL JUNCTION CAPACITANCE

